

Product Bulletin Document #:PB23612Z

Issue Date:03 Nov 2020

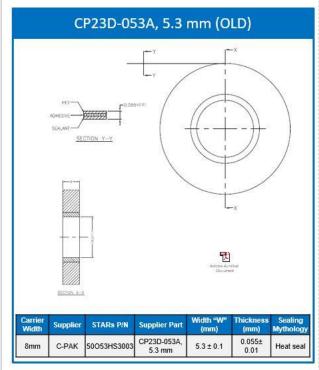
Title of Change:	Change the C Pak cover tape Model from CP23D to CP38 and width from 5.3mm (Milky) to be 5.4mm (Clearly) at Stars Micro
Effective date:	03 Nov 2020
Contact information:	Contact your local ON Semiconductor Sales Office or Pallop.Sathiennet@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Packing-cover tape change
Change Sub-Category(s):	Packing-Cover tape change

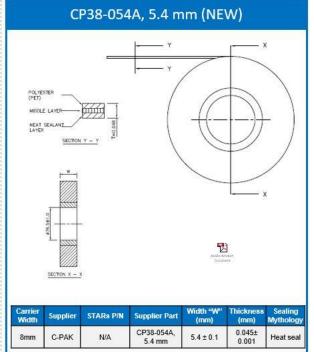
Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
None	None

Description and Purpose:

Change the C Pak cover tape Model from CP23D to CP38 and width from 5.3mm (Milky) to be 5.4mm (Clearly) at Stars Micro "The change will not impact form, fit, or function of product(s)"





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Seal vision:

CP23D-053A, 5.3 mm (OLD)

Cover tape will be easier caused adhesive bleeding out and become the residue contamination.





List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

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